

Single and dual isolated 5 V low drop linear voltage regulators for automotive application

Features



SO-8

Max DC supply voltage	V_S	40 V
Max output voltage tolerance	ΔV_O	$\pm 2\%$
Max dropout voltage	V_{dp}	500 mV
Output current	I_O	50 mA ⁽¹⁾ 2x50 mA ⁽²⁾
Quiescent current	I_{qn}	50 μ A

1. For L5050S - single output
2. For L5050SD - dual output
3. Typical value valid for each single output with $En = LOW$



- AEC-Q100 qualified
- Operating DC supply voltage range 5.6 V to 40 V
- Low dropout voltage
- Low quiescent current consumption
- Precision output voltage 5 V $\pm 2\%$
- Dual electrically isolated voltage regulators (only for L5050SD)
- Enable input for enabling/disabling the voltage regulator
- Thermal shutdown and short circuit protection
- Wide temperature range ($T_j = -40$ °C to 150 °C)



Product status link	
L5050	
Product summary	
Order code	L5050STR, L5050SDTR
Package	SO-8
Packing	Tape and reel

Description

L5050 is a 5 V low dropout linear voltage regulator suitable for automotive applications, available in single (L5050S) or dual isolated (L5050SD) linear output voltage in a SO-8 package. The LDO delivers up to 50 mA (2x50 mA for the dual version) of load current and consumes as low as 5 μ A (per each output in L5050SD) of quiescent current with device disabled. High output voltage accuracy ($\pm 2\%$) is kept over wide temperature range, line and load variation. Enable features (two enables for the dual version) allow enabling or disabling each output. The maximum input voltage is 40 V. The regulator output current is internally limited and the device is protected against short circuit, overload and over temperature conditions. In addition, only low value ceramic capacitor on output is required for stability.

1 Block diagram and pins description

Figure 1. Functional block diagram - L5050S

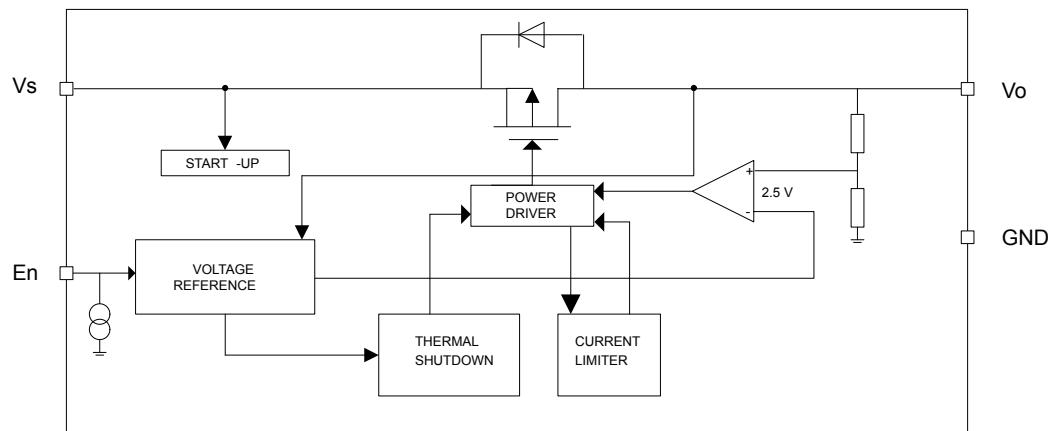
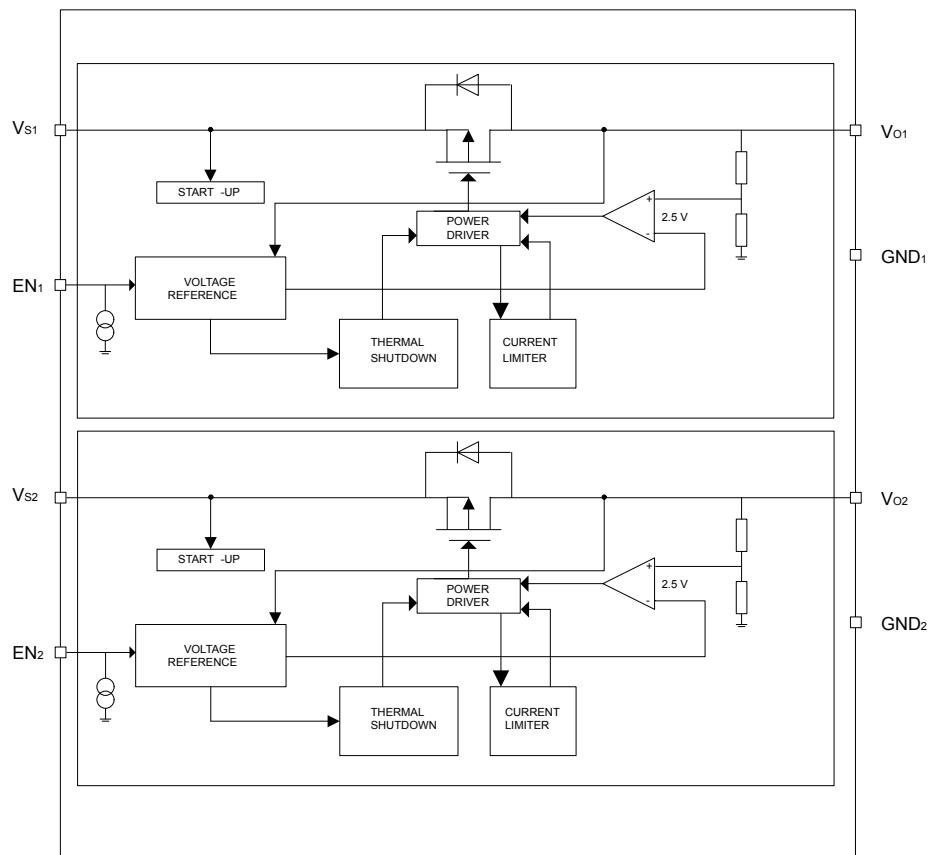


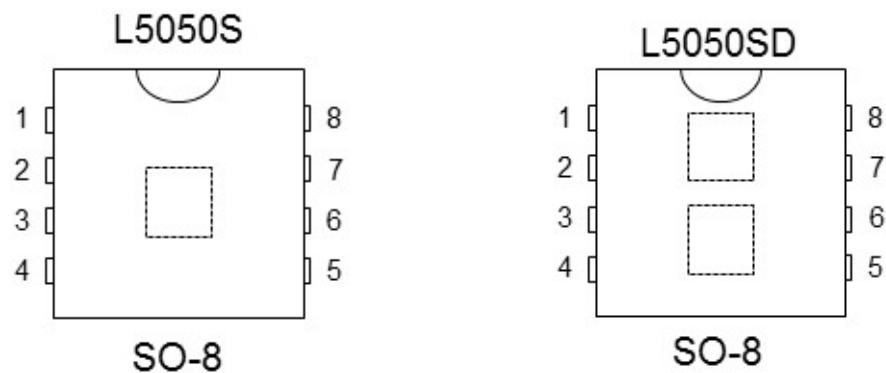
Table 1. L5050S pins description

Pin name	Pin number	Function
N.C.	1	-
GND	2	Ground reference for regulator
V_o	3	5 V regulated output. Block to GND with a ceramic capacitor ($\geq 220 \text{ nF}$ for regulator stability)
N.C.	4	-
N.C.	5	-
V_s	6	Supply voltage, block directly to GND on the IC with a capacitor.
En	7	Enable pin for regulator: high signal to switch the regulator on
N.C.	8	-

Figure 2. Functional block diagram - L5050SD

Table 2. L5050SD pins description

Pin name	Pin number	Function
GND1	1	Ground reference for regulator 1
V_{o1}	2	5 V regulated output 1. Block to GND1 with a ceramic capacitor ($\geq 220 \text{ nF}$ for regulator stability)
GND2	3	Ground reference for regulator 2
V_{o2}	4	5 V regulated output 2. Block to GND2 with a ceramic capacitor ($\geq 220 \text{ nF}$ for regulator stability)
V_{S2}	5	Supply voltage 2, block directly to GND2 on the IC with a capacitor
EN_2	6	Enable pin for regulator 2: • high signal to switch the regulator on
V_{S1}	7	Supply voltage 1, block directly to GND1 on the IC with a capacitor.
EN_1	8	Enable pin for regulator 1: • high signal to switch the regulator on

Figure 3. Pins configuration



2 Electrical specifications

2.1

Absolute maximum ratings

Stressing the device above the rating listed in the [Table 3. Absolute maximum ratings](#): Absolute maximum ratings may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE program and other relevant quality documents.

Table 3. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_s	DC supply voltage	-0.3 to 40	V
I_s	Input current	internally limited	
V_o	DC output voltage	-0.3 to 6	V
I_o	DC output current	internally limited	
V_{En}	Enable input	-0.3 to 40	
T_J	Junction operating temperature	-40 to 150	°C
$V_{ESD\ HBM}$	ESD HBM voltage level (HBM-MIL STD 883C)	±2	kV
$V_{ESD\ CDM}$	ESD CDM voltage level (CDM)	±750 ⁽¹⁾	V

1. ±500 V for En_1 and En_2 (only for L5050SD).

Table 4. Thermal data

Item	Symbol	Parameter	Value ⁽¹⁾	Unit
A.001	Rth-jamb	Thermal resistance junction to ambient	110	°C/W

1. PCB: double layer; FR4 area = 77 mm x 86 mm; PCB thickness = 1.6 mm; Cu thickness = 70 µm (front and back side).

2.2

Electrical characteristics

Values specified in this section are for $V_S = 5.6$ V to 31 V, $T_J = -40$ °C to +150 °C, unless otherwise stated.

Table 5. General

Item	Pin	Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
A.002	V_o	V_o	Output voltage	$V_S = 5.6$ to 31 V; $I_o = 5$ to 50 mA	4.9	5	5.1	V
A.003	V_o	I_{short}	Short circuit current	$V_S = 5.6$ to 31 V	200	380	550	mA
				$V_S = 10.5$ V	200	370	450	
A.004	V_o	$I_{lim}^{(1)}$	Output current limitation	$V_S = 10.5$ V	100	225	450	mA
A.005	V_S, V_o	V_{line}	Line regulation voltage	$V_S = 5.6$ to 18 V; $I_o = 5$ to 50 mA			50	mV
A.006	V_o	V_{load}	Load regulation voltage	$I_o = 5$ to 50 mA, $V_S = 5.6$ to 31 V			55	mV
A.007	V_S, V_o	V_{dp}	Drop voltage	$I_o = 50$ mA			500	mV
A.008	V_S, V_o	SVR	Ripple rejection	$f_r = 100$ Hz ⁽²⁾		60		dB
A.009	V_o	I_{oth_H}	Normal consumption mode output current			4		mA
A.010	V_o	I_{oth_L}	Very low consumption mode output current				0.1	mA
A.011	V_S, V_o	I_{qn}	Current consumption with regulator disabled $I_{qn} = I_{VS} - I_o$	$V_S = 13.5$ V, En = low		5	10	µA
A.012	V_S, V_o	I_{qn_1}	Current consumption with regulator enabled $I_{qn_1} = I_{VS_I0}$	$I_o = 0.1$ mA to 0.3 mA; En = high		50	70	µA
A.013	V_S, V_o	I_{qn_50}	Current consumption with regulator enabled $I_{qn_50} = I_{VS_I0}$	$I_o = I_{oth_H}$ to 50 mA; En = high		2	4.2	mA
A.014		T_w	Thermal protection temperature ⁽³⁾		150		190	°C
A.015		T_{w_hy}	Thermal protection temperature hysteresis			10		°C

1. Measured output current when the output voltage has dropped 200 mV from its nominal value obtained at $V_S = 10.5$ V and $I_o = 25$ mA.
2. Guaranteed by design.
3. Thermal protection is guaranteed by design and characterization.

Table 6. Enable

Item	Pin	Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
A.016	En	V_{En_low}	En input low voltage				1	V
A.017	En	V_{En_high}	En input high voltage		3			V
A.018	En	V_{En_hyst}	En input hysteresis		800			mV
A.019	En	I_{leak}	Pull down current	$V_{En} = 5$ V		3	10	µA

2.3 Electrical characteristics curves

Figure 4. Output voltage vs T_J

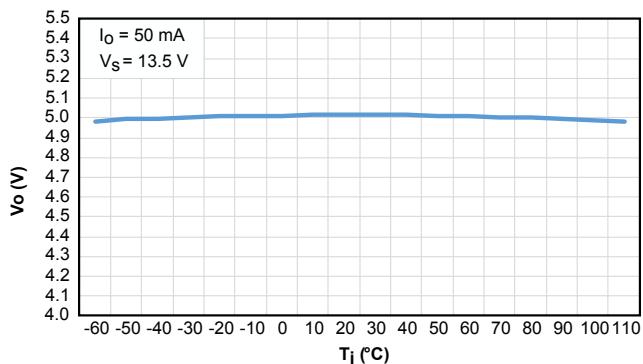


Figure 5. Output voltage vs V_s

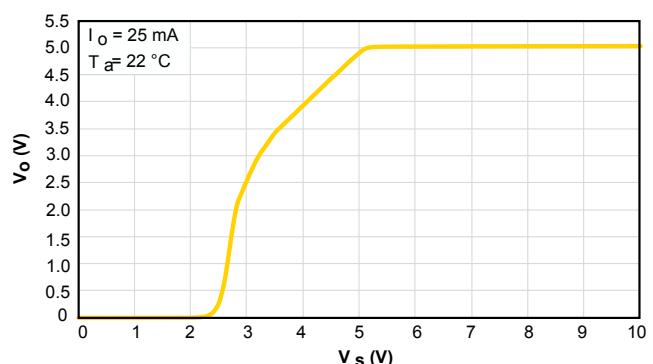


Figure 6. Output voltage vs V_{en}

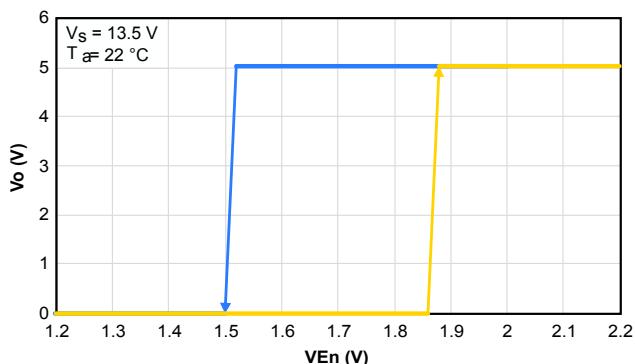


Figure 7. Drop voltage vs output current

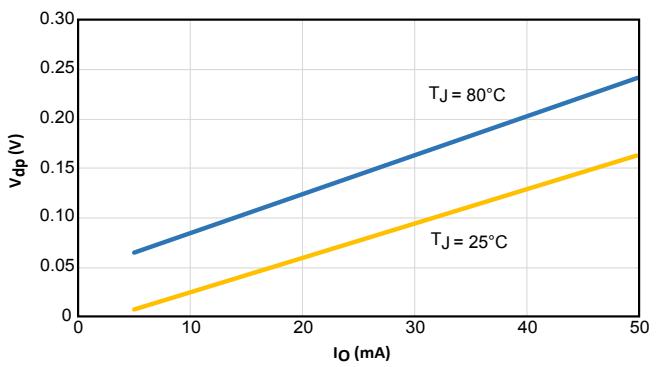


Figure 8. Current consumption vs output current

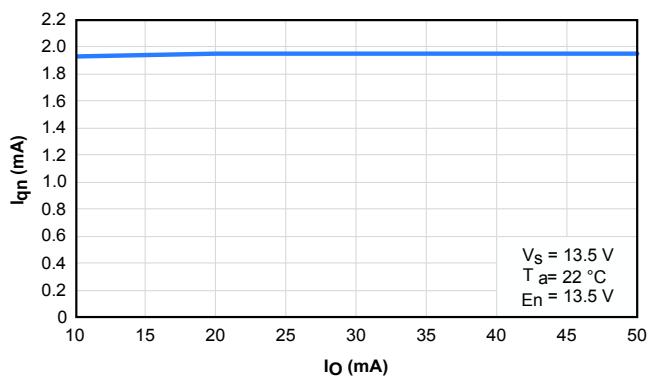


Figure 9. Current consumption vs output current (at light load condition)

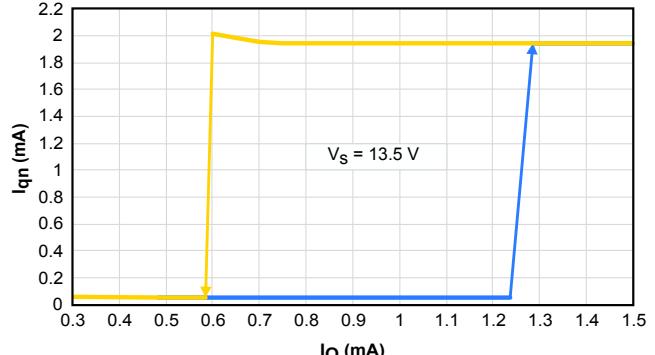


Figure 10. Current consumption vs input voltage ($I_o = 0.15$ mA)

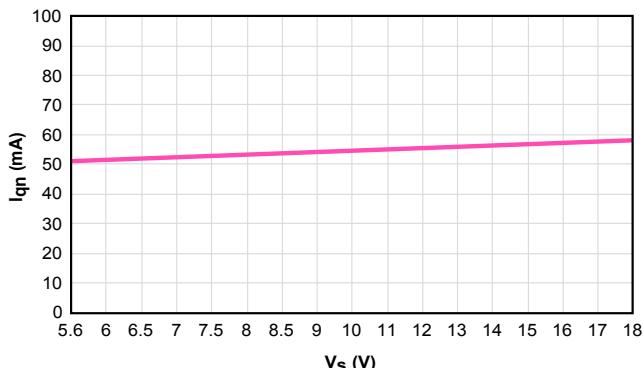


Figure 11. Current consumption vs input voltage ($I_o = 50$ mA)

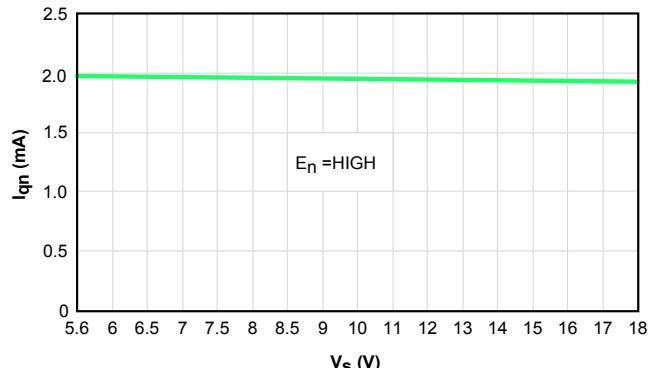


Figure 12. Current limitation vs T_J

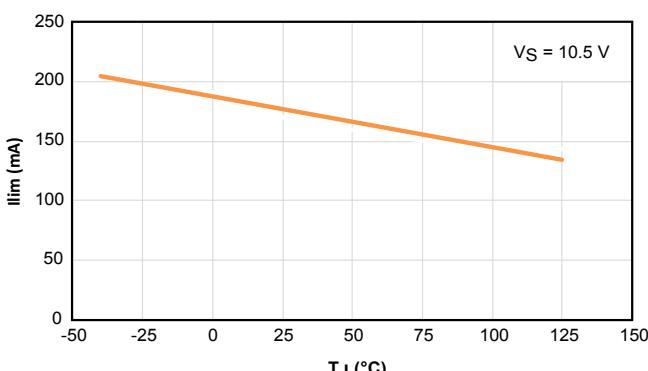


Figure 13. Current limitation vs input voltage

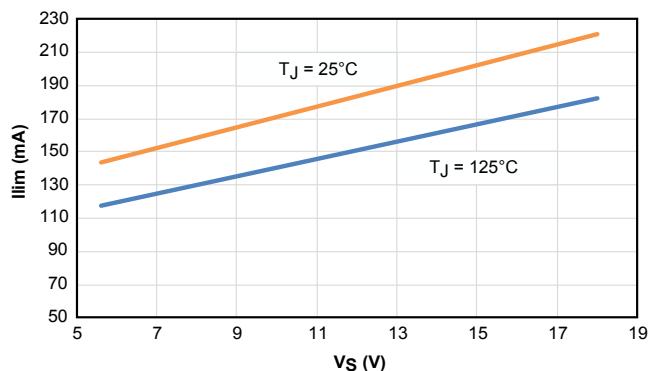


Figure 14. Short-circuit current vs T_J

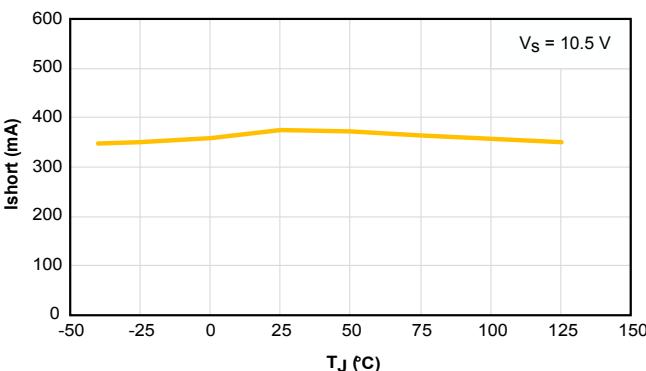


Figure 15. Short-circuit current vs input voltage

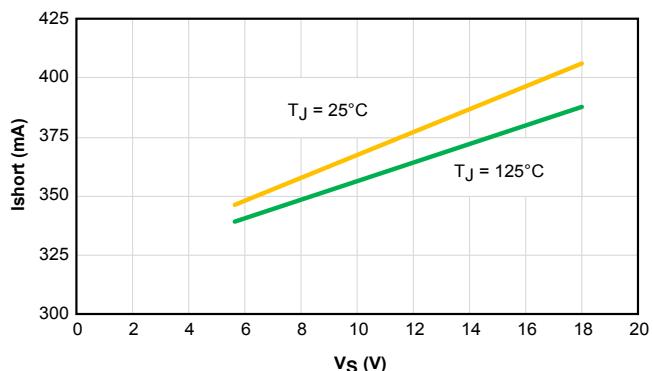


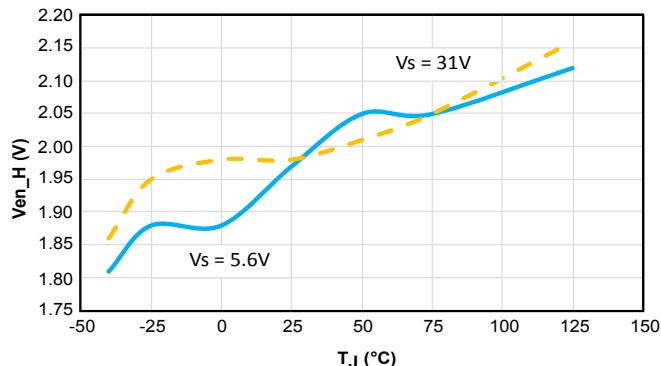
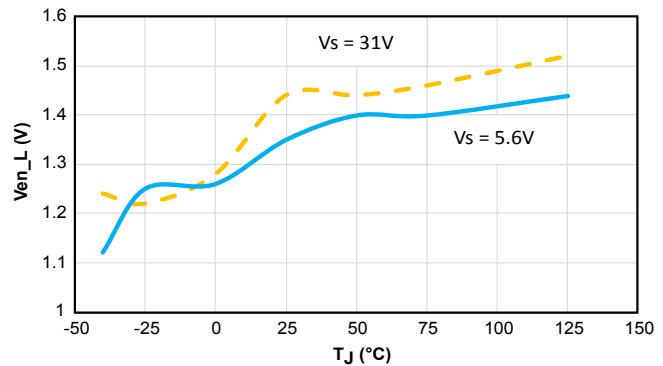
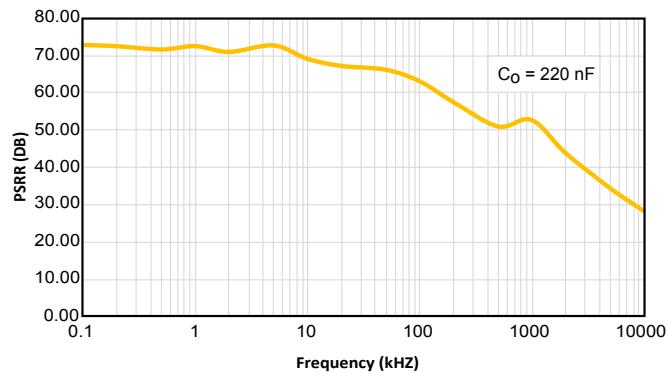
Figure 16. V_{EN_high} vs T_J Figure 17. V_{EN_low} vs T_J 

Figure 18. PSRR



3 Protection features

3.1 Voltage regulator

Voltage regulator uses a p-channel MOS transistor as a regulating element. With that structure, a very low dropout voltage at current up to 50 mA is obtained. The output voltage is regulated up to transient input supply voltage of 40 V. The high-precision of the output voltages ($\pm 2\%$) are obtained with a pre-trimmed reference voltage. The voltage regulator automatically adapts its own quiescent current to the output current level. In light load conditions, the quiescent current goes down to 50 μ A only in low consumption mode (for each regulating element in L5050SD). This procedure features a certain hysteresis on the output current (see [Figure 9. Current consumption vs output current \(at light load condition\)](#)). Short-circuit protection to GND and a thermal shutdown are provided.

Figure 19. Application schematic - L5050S

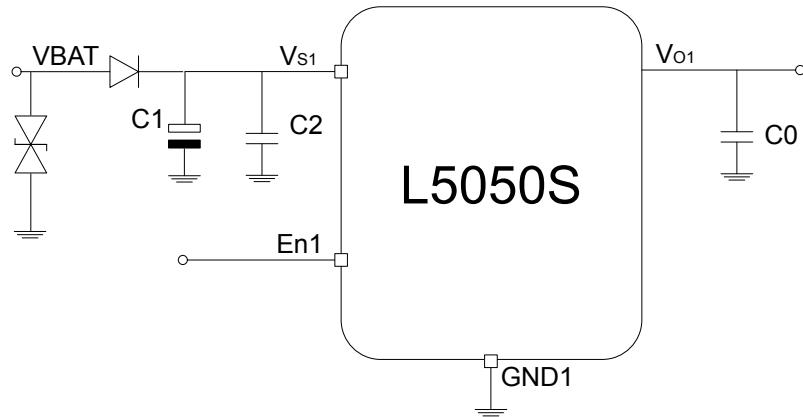


Figure 20. Application schematic - L5050SD - common input voltage

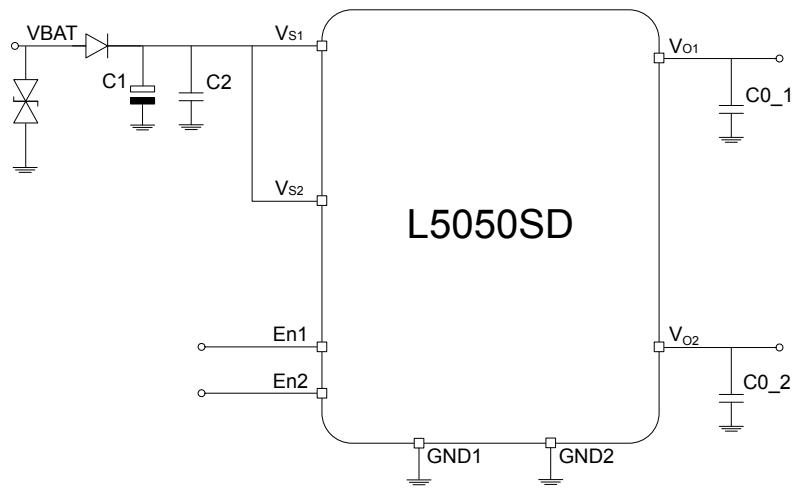
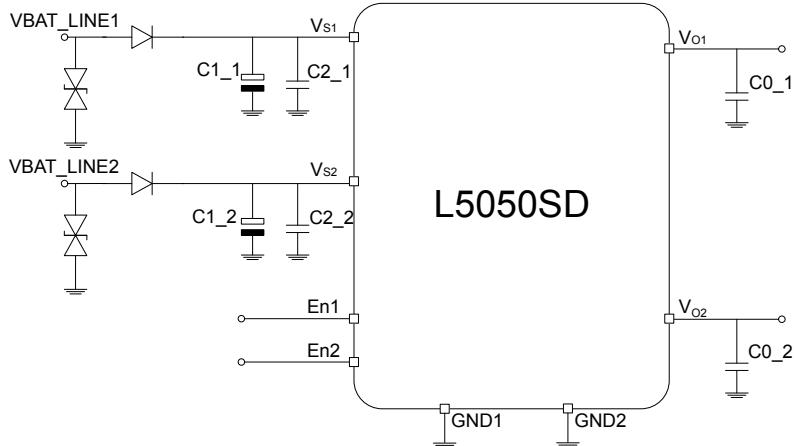


Figure 21. Application schematic - L5050SD - double supply line for the input voltages



The input capacitor C1 is necessary as backup supply for short battery voltage interruption, which may occur on the line. Its value, should be chosen according to the relevant application requirement. The second input capacitor C2 ≥ 220 nF is needed when the C1 is too distant from the VS pin and it compensates smooth line disturbances. The C0 ceramic capacitor, connected to the output pin, is for bypassing to GND the high-frequency noise and it guarantees stability even during sudden line and load variations. Suggested value is C0 = 220 nF with ESR ≥ 100 m Ω . Stability region is reported in the figure below.

Figure 22. Stability region

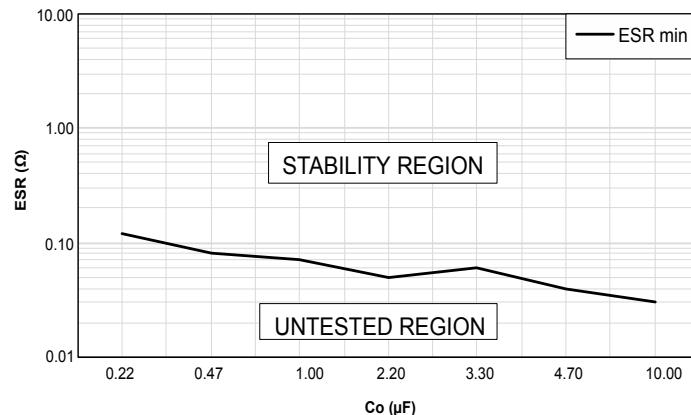
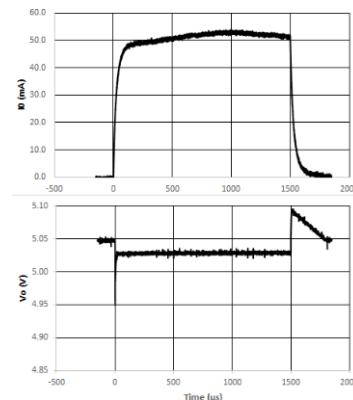


Figure 23. Maximum load variation response



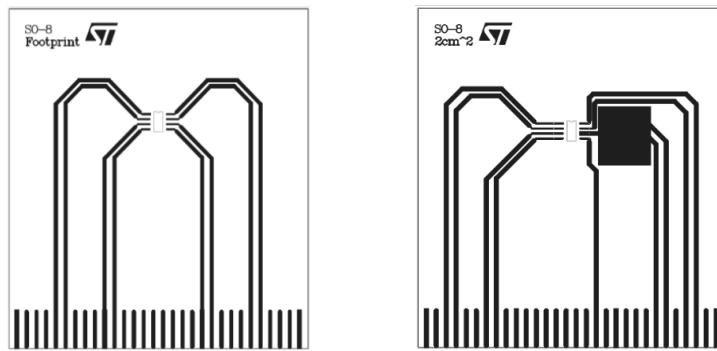
3.2 Enable

L5050 feature enable input (two enable input pins for the L5050SD, one for each voltage regulator).

A high voltage level at the enable input pin switches the regulator element ON. In standby mode, with the enable input pin low, the regulator output is disabled and the current consumption of the corresponding regulator (quiescent current) is typically 5 μ A.

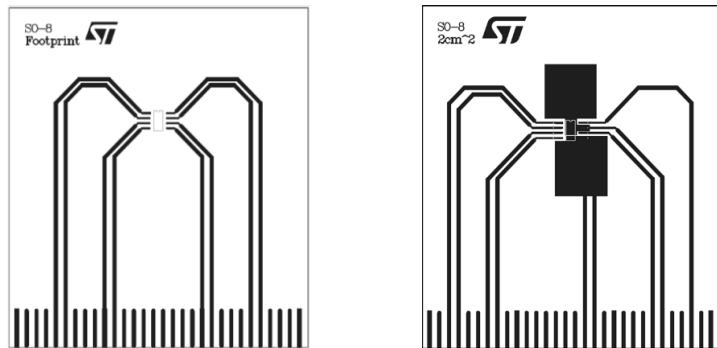
4 Package and PCB thermal data

Figure 24. SO-8 PC board for L5050S



Note: Layout condition of R_{th} and Z_{th} measurements (PCB: double layer; FR4 area = 77 mm x 86 mm; PCB thickness = 1.6 mm; Cu thickness = 70 μ m (front and back side); Cu thickness on vias of 0.025 mm in PCB with a dissipation area of 2cm² (picture on the right)).

Figure 25. SO-8 PC board for L5050SD



Note: Layout condition of R_{th} and Z_{th} measurements (PCB: double layer; FR4 area = 77 mm x 86 mm; PCB thickness = 1.6 mm; Cu thickness = 70 μ m (front and back side); Cu thickness on vias of 0.025 mm in PCB with a dissipation area of two 2cm² for L5050SD (picture on the right)).

Figure 26. Rthj-amb vs PCB copper area in open box free air condition

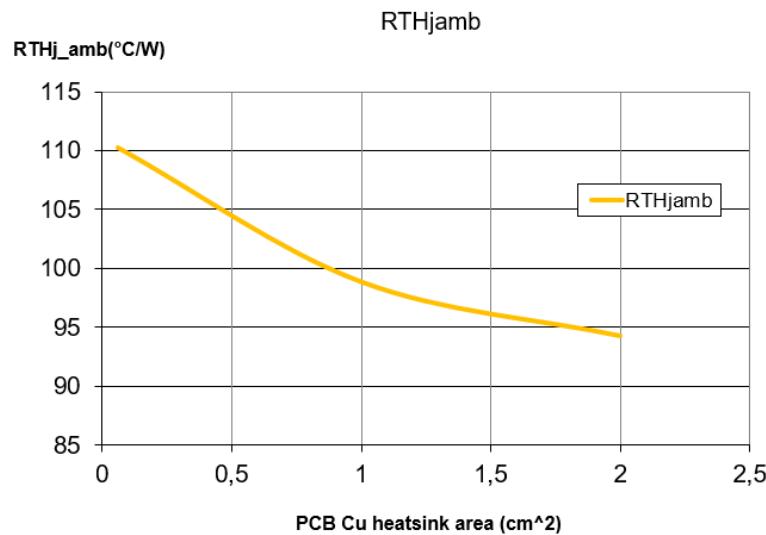


Figure 27. SO-8 thermal impedance junction ambient single pulse (L5050S)

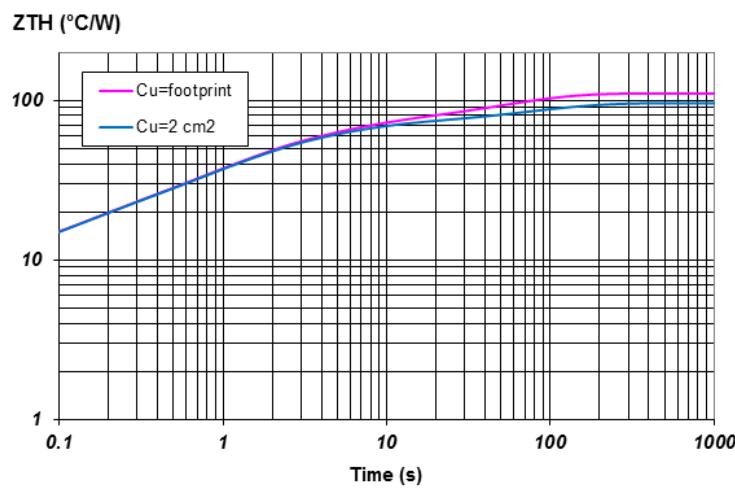
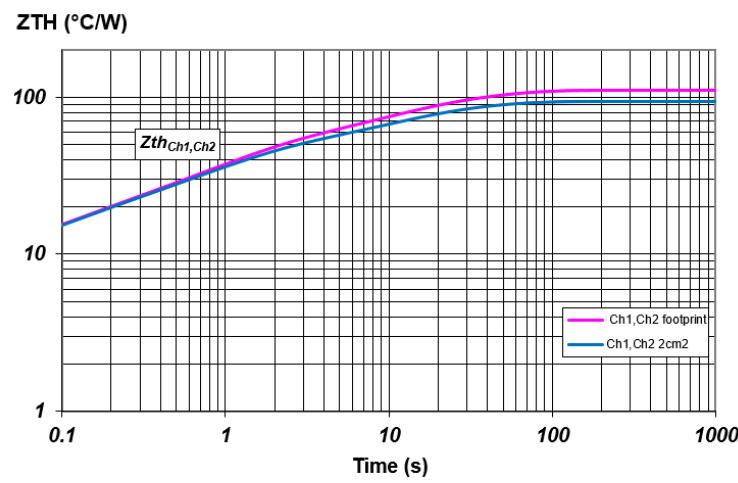


Figure 28. SO-8 thermal impedance junction ambient single pulse (one channel on for L5050SD)



Equation 1: pulse calculation formula

$$Z_{TH\delta} = R_{TH} \cdot \delta + Z_{THtp} (1 - \delta)$$

where $\delta = tp/T$

Figure 29. L5050S thermal fitting model of a V_{reg} in SO-8

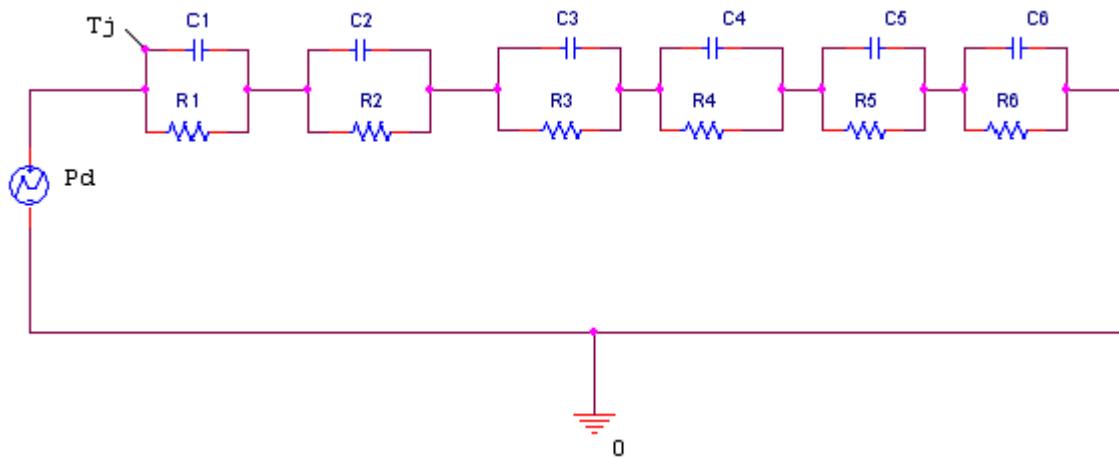


Figure 30. L5050SD Thermal fitting model of a V_{reg} in SO-8

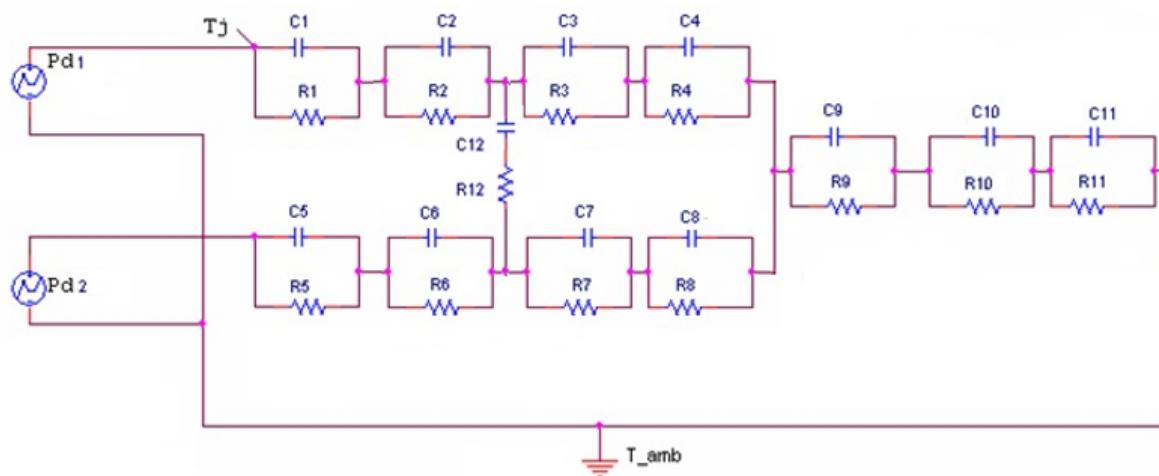


Table 7. L5050S SO-8 thermal parameter

Area/island (cm ²)	FP	2
R1 (°C/W)	3.2	
R2 (°C/W)	4.2	
R3 (°C/W)	7.9	
R4 (°C/W)	26.5	
R5 (°C/W)	27	
R6 (°C/W)	41.6	27.1
C1 (W·s/°C)	0.00001	
C1 (W·s/°C)	0.0015	
C3 (W·s/°C)	0.014	
C4 (W·s/°C)	0.04	
C5 (W·s/°C)	0.165	
C6 (W·s/°C)	1.4	3

Table 8. L5050SD SO-8 thermal parameter

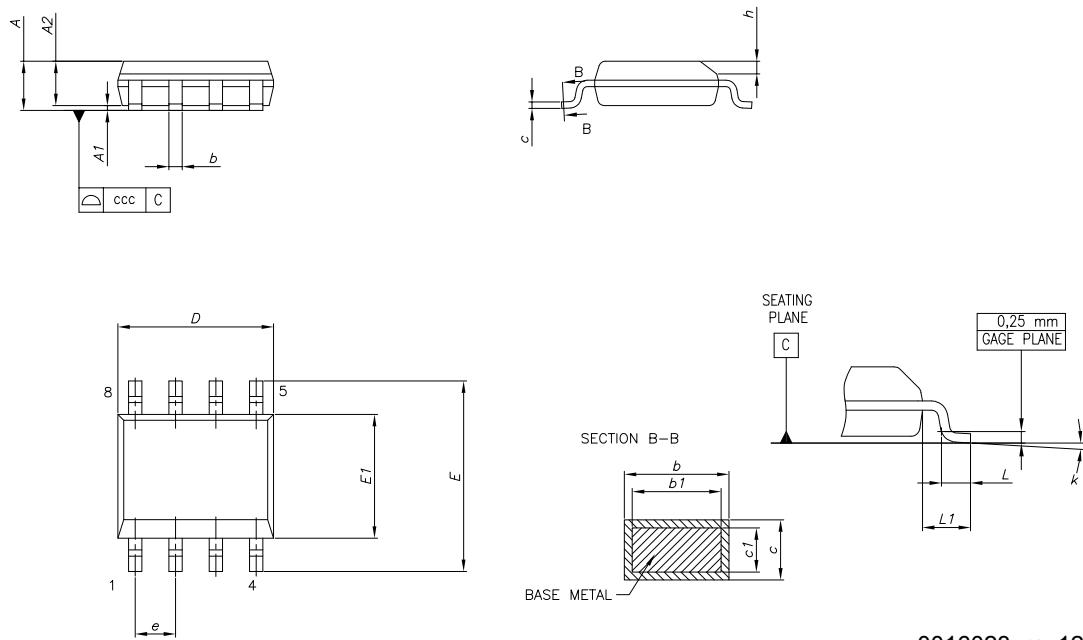
Area/island (cm ²)	FP	2
R1 - R5 (°C/W)	3.2	
R2 - R6 (°C/W)	4.2	
R3 - R7 (°C/W)	7.9	
R4 - R8 (°C/W)	8	
R9 (°C/W)	26	24
R10(°C/W)	28	23
R11 (°C/W)	33	24
R12 (°C/W)	50	50
C1 - C5 (W·s/°C)	0.00001	
C1 - C6 (W·s/°C)	0.0015	
C3 - C7 (W·s/°C)	0.014	
C4 - C8 (W·s/°C)	0.06	
C9 (W·s/°C)	0.05	
C10 (W·s/°C)	0.35	0.45
C11 (W·s/°C)	1	1.2
C12 (W·s/°C)	0.1	0.1

5 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

5.1 SO-8 package information

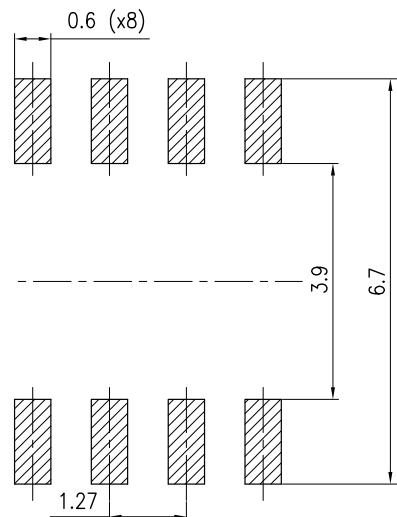
Figure 31. SO-8 package outline



0016023_rev12

Table 9. SO-8 mechanical data

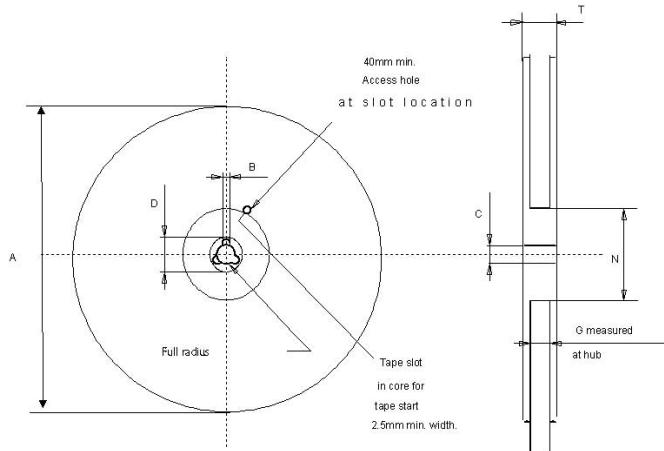
Dim.	mm		
	Min.	Typ.	Max.
A			1.75
A1	0.10		0.25
A2	1.25		
b	0.28		0.48
c	0.17		0.23
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e		1.27	
h	0.25		0.50
L	0.40		1.27
L1		1.04	
k	0°		8°
ccc			0.10

Figure 32. SO-8 recommended footprint (dimensions are in mm)

0016023_Rev12

5.2 SO-8 packaging information

Figure 33. SO-8 tape and reel shipment (suffix "TR")



Reel dimensions

Baseq .ty	2500
Bulkq .ty	2500
A (m ax)	330
B (min)	1.5
C (± 0.2)	13
F	20.2
G (+2 /- 0)	12.4
N (min)	60
T (m ax)	18.4

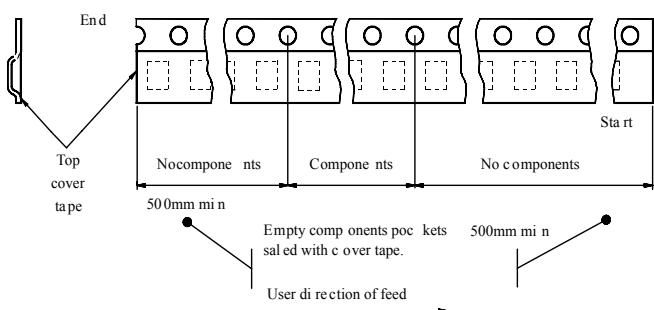
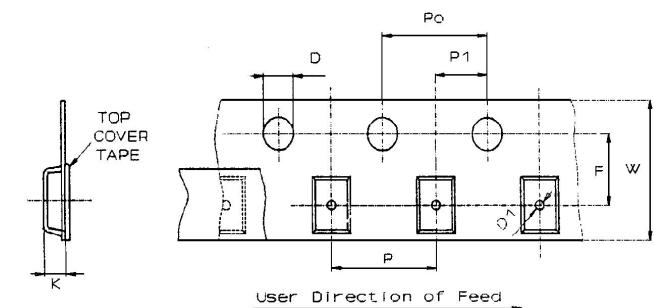
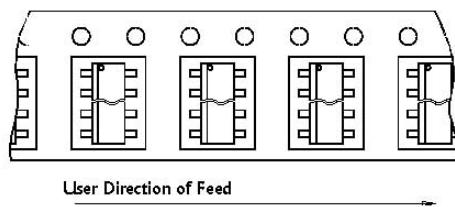
All dimensions are in mm.

Tape dimensions

According to Electronic Industries Association (EIA) Standard 481 rev.A, Feb. 1986

Tapewidth	W	12
Tape hole spacing	P0 (± 0.1)	4
Componentsspacing	P	8
Hole diameter	D ($+0.1/-0$)	1.5
Hole diameter	D1 (m in)	1.5
Hole position	F (± 0.05)	5.5
Compartment depth	K (max)	4.5
Holespacing	P1 (± 0.1)	2

All dimensions are in mm.



Revision history

Table 10. Document revision history

Date	Version	Changes
19-Apr-2021	1	Initial release.

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